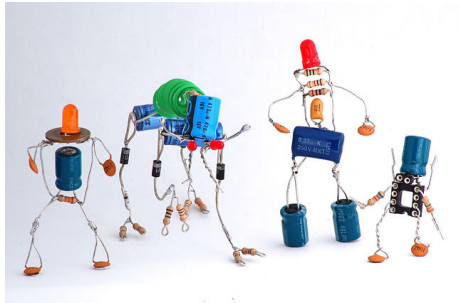


Instrumentación y Control - COMPONENTES ELECTRÓNICOS

22 de Agosto de 2018



Clasificación según la estructura física

Discretos: elementos individuales que cumplen un tarea específica



Integrados: circuitos compuestos por varios elementos



Clasificación según la función específica

Pasivos: solo consumen o almacenan energía

- ▶ Resistencias
- ▶ Capacitores
- ▶ Inductores

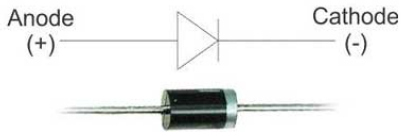
Activos: transfieren energía, modifican el nivel y la forma de las señales

- ▶ Diodos
- ▶ Transistores

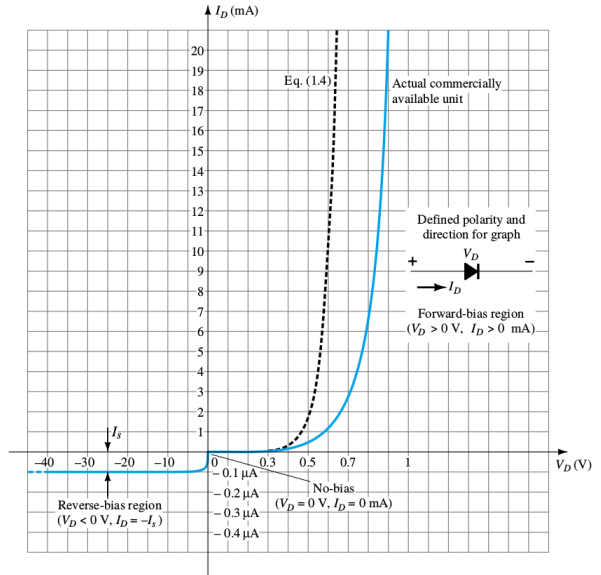
Electromecánicos: conjugan operaciones eléctricas y funciones mecánicas

- ▶ Relays
- ▶ Piezoeléctricos
- ▶ Fusibles

Diodos: Esquemático y curva característica



$$I_D(V_D) = I_S \left\{ \exp\left(\frac{q V_D}{\eta K_B T}\right) - 1 \right\}$$



Diodos: Especificación de datos

- ▶ Potencial de conducción en directa V_F
- ▶ Corriente máxima en directa I_F
- ▶ Corriente de saturación inversa I_R
- ▶ Potencial de ruptura $PIV / PRV / V(BR) / V_R$
- ▶ Potencia disipada P_D
- ▶ Capacitancia C_T
- ▶ Tiempo de recuperación t_{rr}

Diodos: Hoja de datos

Absolute Maximum Ratings*

$T_A = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	100	V
$I_{F(AV)}$	Average Rectified Forward Current	200	mA
I_{FSM}	Non-repetitive Peak Forward Surge Current		
	Pulse Width = 1.0 second	1.0	A
	Pulse Width = 1.0 microsecond	4.0	A
T_{stg}	Storage Temperature Range	-65 to +200	$^{\circ}\text{C}$
T_J	Operating Junction Temperature	175	$^{\circ}\text{C}$

Diodos: Hoja de datos

Thermal Characteristics

Symbol	Characteristic	Max	Units
		1N/FDLL 914/A/B / 4148 / 4448	
P_D	Power Dissipation	500	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	300	°C/W

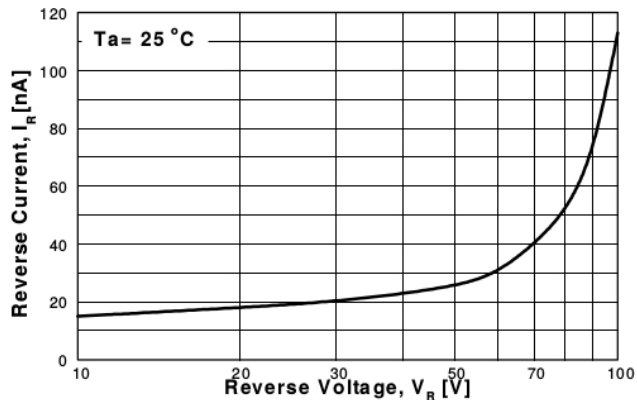
Diodos: Hoja de datos

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
V_R	Breakdown Voltage	$I_R = 100\ \mu\text{A}$	100		V
		$I_R = 5.0\ \mu\text{A}$	75		V
V_F	Forward Voltage	$I_F = 5.0\ \text{mA}$	620	720	mV
		$I_F = 5.0\ \text{mA}$	630	730	mV
		$I_F = 10\ \text{mA}$		1.0	V
		$I_F = 20\ \text{mA}$		1.0	V
		$I_F = 20\ \text{mA}$		1.0	V
		$I_F = 100\ \text{mA}$		1.0	V
I_R	Reverse Current	$V_R = 20\ \text{V}$		25	nA
		$V_R = 20\ \text{V}, T_A = 150^\circ\text{C}$		50	μA
		$V_R = 75\ \text{V}$		5.0	μA
C_T	Total Capacitance	$V_R = 0, f = 1.0\ \text{MHz}$		2.0	pF
		$V_R = 0, f = 1.0\ \text{MHz}$		4.0	pF
t_{rr}	Reverse Recovery Time	$I_F = 10\ \text{mA}, V_R = 6.0\ \text{V} (60\text{mA}),$ $I_{rr} = 1.0\ \text{mA}, R_L = 100\Omega$		4.0	ns

Diodos: Hoja de datos



GENERAL RULE: The Reverse Current of a diode will approximately double for every ten (10) Degree C increase in Temperature

Figure 2. Reverse Current vs Reverse Voltage
IR - 10 to 100 V

Diodos: Hoja de datos

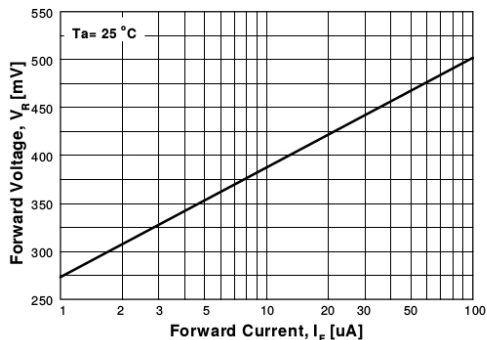


Figure 3. Forward Voltage vs Forward Current
VF - 1 to 100 uA

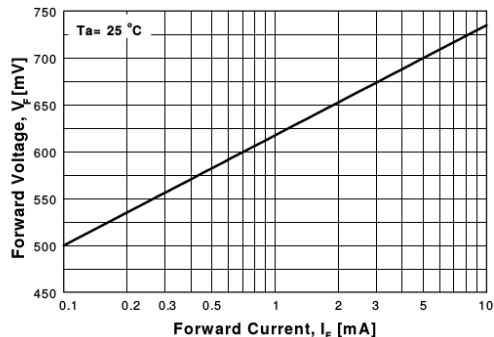


Figure 4. Forward Voltage vs Forward Current
VF - 0.1 to 10 mA

Ojo, pueden haber typos!

Diodos: Hoja de datos

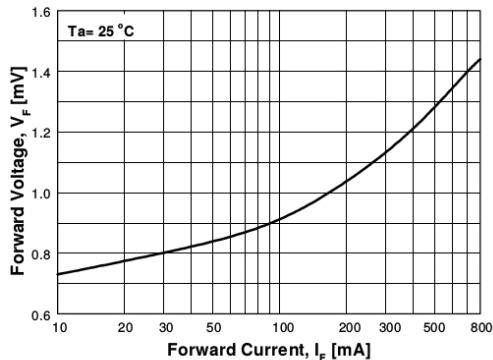


Figure 5. Forward Voltage vs Forward Current
VF - 10 to 800 mA

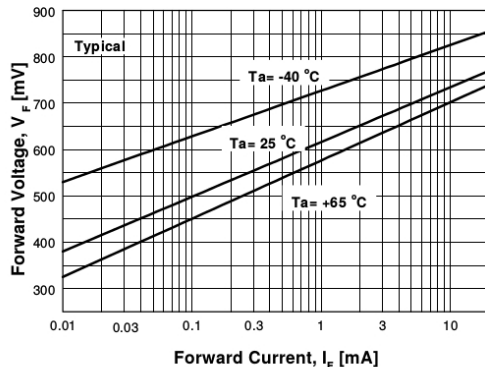


Figure 6. Forward Voltage
vs Ambient Temperature
VF - 0.01 - 20 mA (-40 to +65 Deg C)

Diodos: Hoja de datos

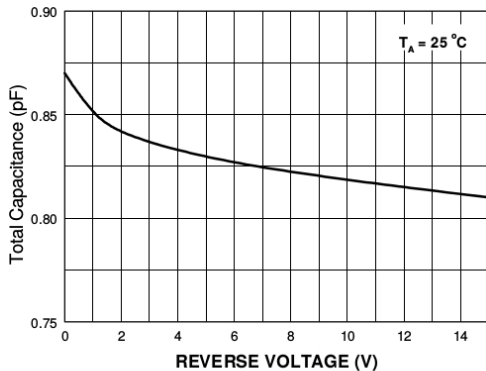


Figure 7. Total Capacitance

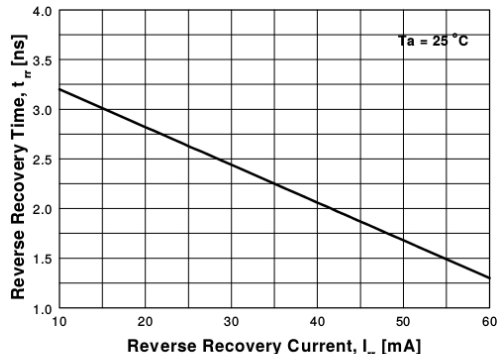


Figure 8. Reverse Recovery Time vs Reverse Recovery Current

Capacitor variable (mirar que pasa con otros diodos)

Diodos: Hoja de datos

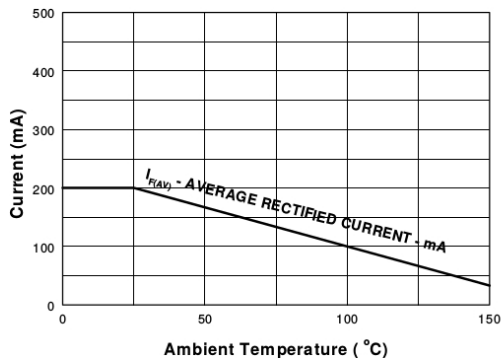


Figure 9. Average Rectified Current ($I_{F(AV)}$) versus Ambient Temperature (T_A)

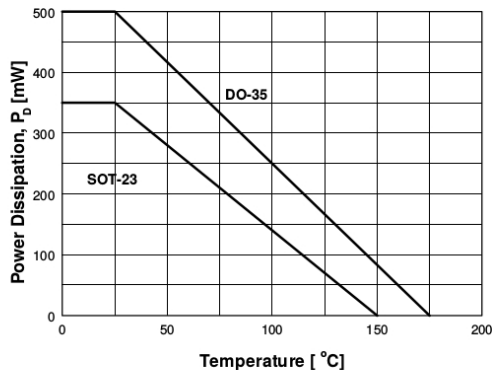
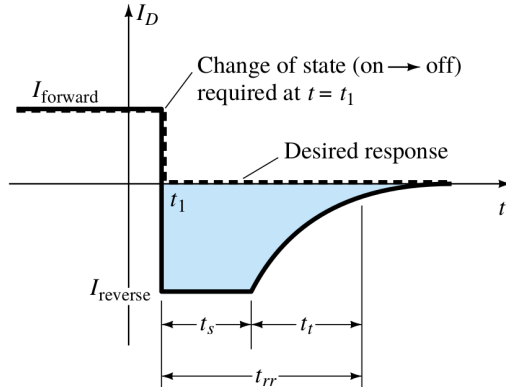


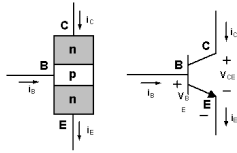
Figure 10. Power Derating Curve

Diodos: Propuesta de trabajo

Medir el tiempo de respuesta inverso t_{rr} para varios dispositivos



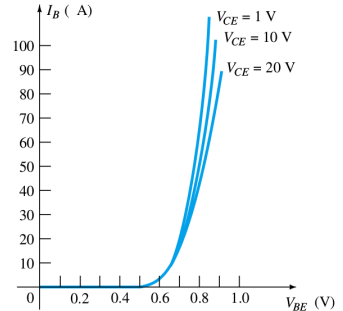
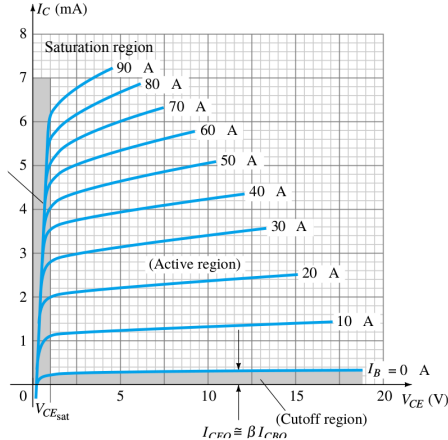
BJT: Esquemático y curvas características



$$V_{BE} \approx 0,7 \text{ V}$$

$$I_C + I_B = I_E$$

$$I_C = \beta I_B$$



BJT: Especificación de datos

- ▶ Zona de ruptura
- ▶ Corrientes y temperaturas máximas
- ▶ Factores de ajuste
- ▶ Ganancia de corriente

BJT: Hoja de datos

Absolute Maximum Ratings $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage : BC546	80	V
	: BC547/550	50	V
	: BC548/549	30	V
V_{CEO}	Collector-Emitter Voltage : BC546	65	V
	: BC547/550	45	V
	: BC548/549	30	V
V_{EBO}	Emitter-Base Voltage : BC546/547	6	V
	: BC548/549/550	5	V
I_C	Collector Current (DC)	100	mA
P_C	Collector Power Dissipation	500	mW
T_J	Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-65 ~ 150	$^\circ\text{C}$

BJT: Hoja de datos

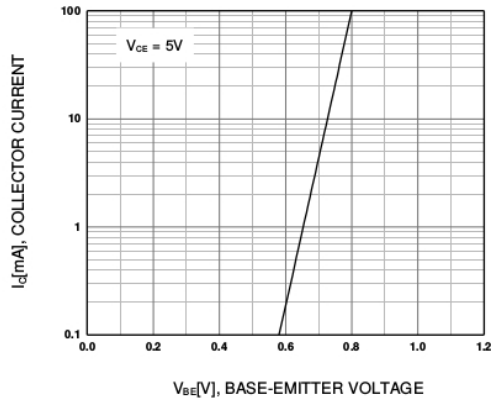
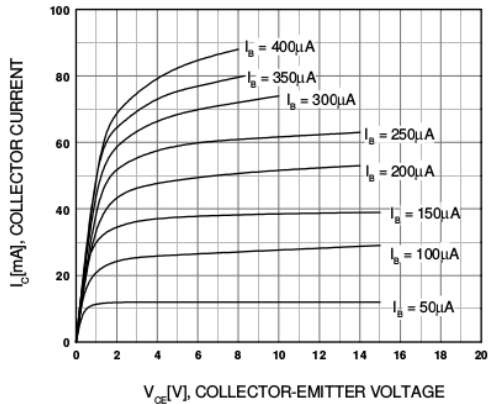
Electrical Characteristics $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
I_{CBO}	Collector Cut-off Current	$V_{CB}=30\text{V}$, $I_E=0$			15	nA
h_{FE}	DC Current Gain	$V_{CE}=5\text{V}$, $I_C=2\text{mA}$	110		800	
$V_{CE}(\text{sat})$	Collector-Emitter Saturation Voltage	$I_C=10\text{mA}$, $I_B=0.5\text{mA}$ $I_C=100\text{mA}$, $I_B=5\text{mA}$		90 200	250 600	mV mV
$V_{BE}(\text{sat})$	Base-Emitter Saturation Voltage	$I_C=10\text{mA}$, $I_B=0.5\text{mA}$ $I_C=100\text{mA}$, $I_B=5\text{mA}$		700 900		mV mV
$V_{BE}(\text{on})$	Base-Emitter On Voltage	$V_{CE}=5\text{V}$, $I_C=2\text{mA}$ $V_{CE}=5\text{V}$, $I_C=10\text{mA}$	580	660	700 720	mV mV
f_T	Current Gain Bandwidth Product	$V_{CE}=5\text{V}$, $I_C=10\text{mA}$, $f=100\text{MHz}$		300		MHz
C_{ob}	Output Capacitance	$V_{CB}=10\text{V}$, $I_E=0$, $f=1\text{MHz}$		3.5	6	pF
C_{ib}	Input Capacitance	$V_{EB}=0.5\text{V}$, $I_C=0$, $f=1\text{MHz}$		9		pF
NF	Noise Figure : BC546/547/548	$V_{CE}=5\text{V}$, $I_C=200\mu\text{A}$		2	10	dB
	: BC549/550	$f=1\text{KHz}$, $R_G=2\text{K}\Omega$		1.2	4	dB
	: BC549	$V_{CE}=5\text{V}$, $I_C=200\mu\text{A}$		1.4	4	dB
	: BC550	$R_G=2\text{K}\Omega$, $f=30\sim 15000\text{MHz}$		1.4	3	dB

h_{FE} Classification

Classification	A	B	C
h_{FE}	110 ~ 220	200 ~ 450	420 ~ 800

BJT: Hoja de datos



BJT: Hoja de datos

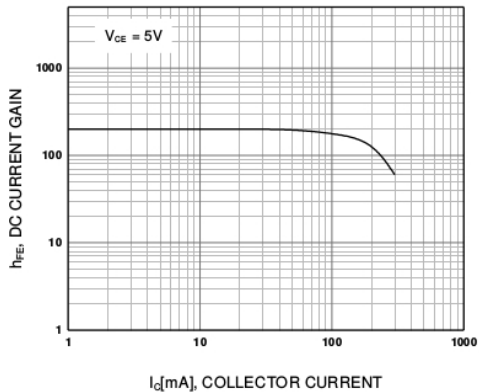


Figure 3. DC current Gain

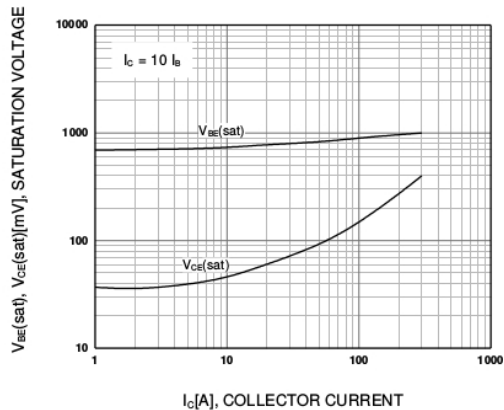


Figure 4. Base-Emitter Saturation Voltage
Collector-Emitter Saturation Voltage

BJT: Hoja de datos

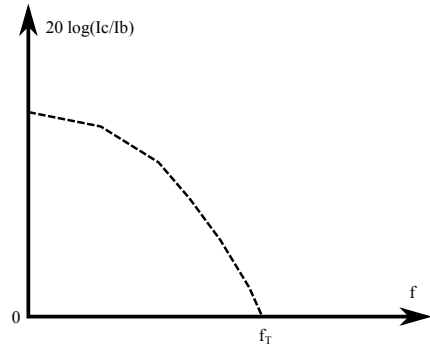
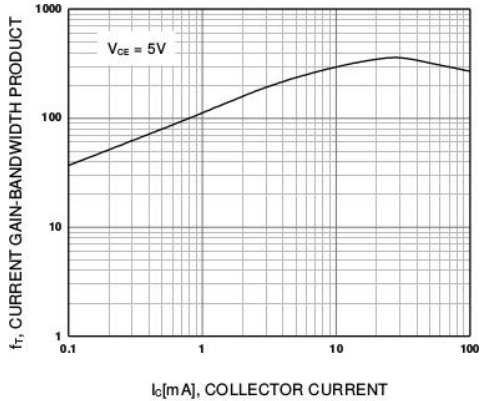
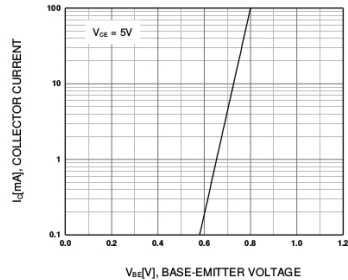
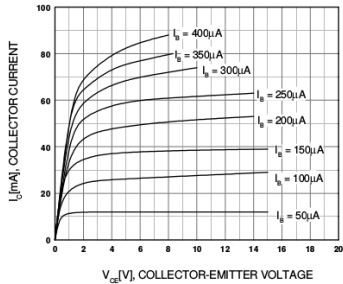


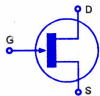
Figure 6. Current Gain Bandwidth Product

BJT: Propuesta de trabajo

Medir curva característica I_C vs. V_{CE}



JFET: Esquemático y curvas características

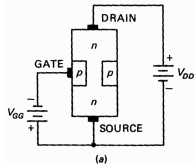


N-Channel JFET

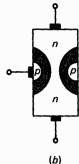


P-Channel JFET

Schematic Symbols For JFETs



(a)

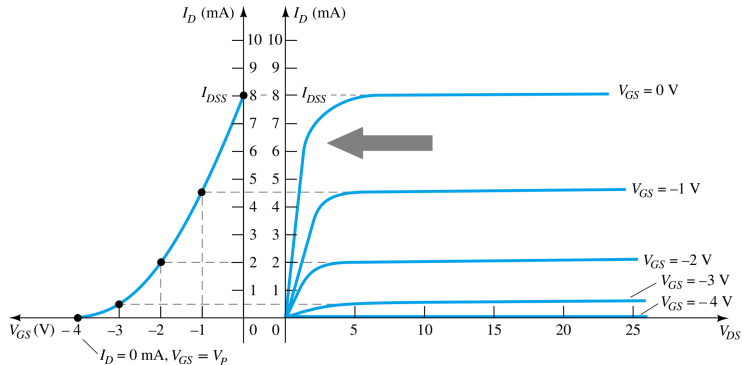


(b)

$$I_G = 0$$

$$I_D = I_S$$

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$



JFET: Hoja de datos

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain – Source Voltage	V_{DS}	25	Vdc
Drain – Gate Voltage	V_{DG}	25	Vdc
Gate – Source Voltage	V_{GS}	–25	Vdc
Gate Current	I_G	10	mAdc
Total Device Dissipation @ $T_A = 25^{\circ}\text{C}$ Derate above 25°C	P_D	350 2.8	mW mW/ $^{\circ}\text{C}$
Junction Temperature Range	T_J	125	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	–65 to +150	$^{\circ}\text{C}$

JFET: Hoja de datos

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Gate – Source Breakdown Voltage ($I_G = -10\ \mu\text{Adc}$, $V_{DS} = 0$)	$V_{(BR)GSS}$	-25	–	Vdc
Gate Reverse Current ($V_{GS} = -15\ \text{Vdc}$, $V_{DS} = 0$) ($V_{GS} = -15\ \text{Vdc}$, $V_{DS} = 0$, $T_A = 100^\circ\text{C}$)	I_{GSS}	– –	-2.0 -2.0	nAdc μAdc
Gate – Source Cutoff Voltage ($V_{DS} = 15\ \text{Vdc}$, $I_D = 2.0\ \text{nAdc}$)	$V_{GS(off)}$	–	-8.0	Vdc
Gate – Source Voltage ($V_{DS} = 15\ \text{Vdc}$, $I_D = 0.2\ \text{mAdc}$)	V_{GS}	-0.5	-7.5	Vdc
ON CHARACTERISTICS				
Zero – Gate – Voltage Drain Current (Note 1) ($V_{DS} = 15\ \text{Vdc}$, $V_{GS} = 0\ \text{Vdc}$)	I_{DSS}	2.0	20	mAdc

JFET: Propuesta de trabajo

Fuente de corriente / Resistencia controlado por tensión

